

PATENT NUMBER

lit **O.I.P.E.**
SCANNED **Q.A.** 15

PATENT DATE

EXAMINER *Warrington*

Chin Liap

3744

Method of electrically connecting semiconductor chip to solder balls on ball grid array package

PTO-2040
12/99

ORIGINAL

CROSS REFERENCE(S)

CLASS

SUBCLASS

CLASS

SUBCLASS (ONE SUBCLASS PER BLOCK)

INTERNATIONAL CLASSIFICATION

☐ Continued on Issue Slip Inside File Jacket

**TERMINAL
DISCLAIMER**

DRAWINGS

CLAIMS ALLOWED

Sheets Drwg

Figs. Drwg.

Print Fig

Total Claims[Print Claim for O.G.](#)

☒ The term of this patent subsequent to _____ (date) has been disclaimed.

☐ The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____

☐ The terminal ____ months of this patent have been disclaimed.

(Assistant Examiner)

(Date)

(Primary Examiner)

• (Date)

(Legal Instruments Examiner)

(Date)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

ISSUE BATCH NUMBER

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Form **PTO-436A**
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(FACE)